



**MAXIMUM RATINGS<sup>(1)</sup>**

Sym	Parameter	Value	Unit
V <sub>CC</sub>	Power Supply Pin with Respect to GND	-0.5 to +7	V
V <sub>TERM</sub>	Terminal Voltage with Respect to GND (up to 7.0V)	-0.5 to V <sub>CC</sub> + 0.5	V
T <sub>A</sub>	Operating Temperature	-55 to +125	°C
T <sub>BIAS</sub>	Temperature Under Bias	-55 to +125	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>T</sub>	Power Dissipation	1.0	W
I <sub>OUT</sub>	DC Output Current	50	mA

**RECOMMENDED OPERATING CONDITIONS**

Grade <sup>(2)</sup>	Ambient Temp	GND	V <sub>CC</sub>
Commercial	0°C to 70°C	0V	5.0V ± 10%
Industrial	-40°C to +85°C	0V	5.0V ± 10%
Military	-55°C to +125°C	0V	5.0V ± 10%

**CAPACITANCES<sup>(4)</sup>**(V<sub>CC</sub> = 5.0V, T<sub>A</sub> = 25°C, f = 1.0MHz)

Sym	Parameter	Conditions	Typ	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	5	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	7	pF

**DC ELECTRICAL CHARACTERISTICS**(Over Recommended Operating Temperature & Supply Voltage)<sup>(2)</sup>

Sym	Parameter	Test Conditions	P4C116		P4C116L		Unit	
			Min	Max	Min	Max		
V <sub>IH</sub>	Input High Voltage		2.2	V <sub>CC</sub> + 0.5	2.2	V <sub>CC</sub> + 0.5	V	
V <sub>IL</sub>	Input Low Voltage		-0.5 <sup>(3)</sup>	0.8	-0.5 <sup>(3)</sup>	0.8	V	
V <sub>HC</sub>	CMOS Input High Voltage		V <sub>CC</sub> - 0.2	V <sub>CC</sub> + 0.5	V <sub>CC</sub> - 0.2	V <sub>CC</sub> + 0.5	V	
V <sub>LC</sub>	CMOS Input Low Voltage		-0.5 <sup>(3)</sup>	0.2	-0.5 <sup>(3)</sup>	0.2	V	
V <sub>CD</sub>	Input Clamp Diode Voltage	V <sub>CC</sub> = Min, I <sub>IN</sub> = -18 mA		-1.2		-1.2	V	
V <sub>OL</sub>	Output Low Voltage (TTL Load)	I <sub>OL</sub> = +8 mA, V <sub>CC</sub> = Min		0.4		0.4	V	
V <sub>OH</sub>	Output High Voltage (TTL Load)	I <sub>OH</sub> = -4 mA, V <sub>CC</sub> = Min	2.4		2.4		V	
I <sub>LI</sub>	Input Leakage Current	V <sub>CC</sub> = Max, V <sub>IN</sub> = GND to V <sub>CC</sub>	MIL	-10	+10	-5	+5	µA
			IND/COM	-5	+5	N/A	N/A	
I <sub>LO</sub>	Output Leakage Current	V <sub>CC</sub> = Max, $\overline{CE} = V_{IH}$ , V <sub>OUT</sub> = GND to V <sub>CC</sub>	MIL	-10	+10	-5	+5	µA
			IND/COM	-5	+5	N/A	N/A	
I <sub>SB</sub>	Standby Power Supply Current (TTL Input Levels)	$\overline{CE} \geq V_{IH}$ , V <sub>CC</sub> = Max, f = Max, Outputs Open	MIL	—	30	—	20	mA
			IND/COM	—	20	—	N/A	
I <sub>SB1</sub>	Standby Power Supply Current (CMOS Input Levels)	$\overline{CE} \geq V_{HC}$ , V <sub>CC</sub> = Max, f = 0, Outputs Open V <sub>IN</sub> ≤ V <sub>LC</sub> or V <sub>IN</sub> ≥ V <sub>HC</sub>	MIL	—	15	—	1	mA
			IND/COM	—	10	—	N/A	

N/A = Not applicable



### DATA RETENTION CHARACTERISTICS (P4C116L Military Temperature Only)

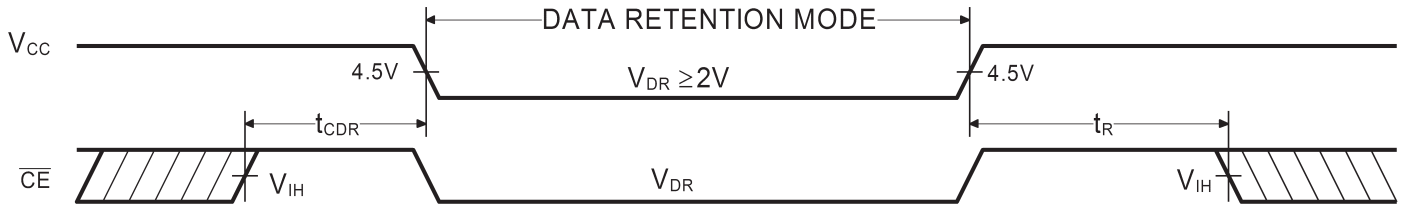
Sym	Parameter	Test Conditions	Min	Typ* V <sub>CC</sub> =		Max V <sub>CC</sub> =		Unit
				2.0V	3.0V	2.0V	3.0V	
V <sub>DR</sub>	V <sub>CC</sub> for Data Retention		2.0					V
I <sub>CCDR</sub>	Data Retention Current	$\overline{CE} \geq V_{CC} - 0.2V,$ $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$		10	15	600	900	μA
t <sub>CDR</sub>	Chip Deselect to Data Retention Time		0					ns
t <sub>R</sub> †	Operation Recovery Time		t <sub>RC</sub> §					ns

\* T<sub>A</sub> = +25°C

§ t<sub>RC</sub> = Read Cycle Time

† This Parameter is guaranteed but not tested

### DATA RETENTION WAVEFORM



### POWER DISSIPATION CHARACTERISTICS VS. SPEED

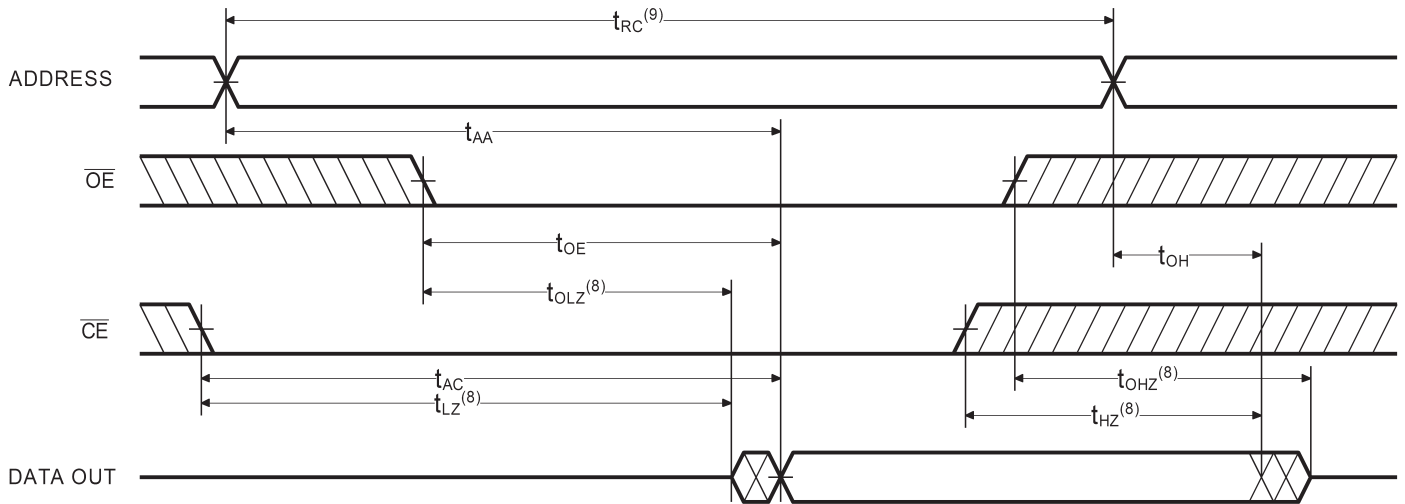
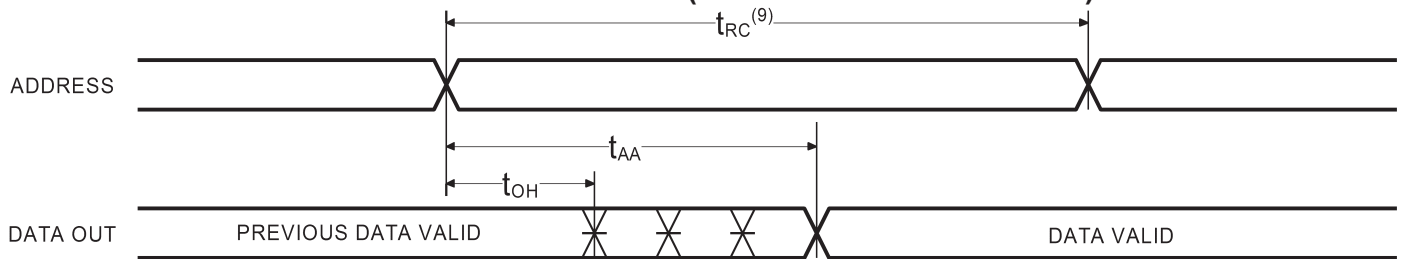
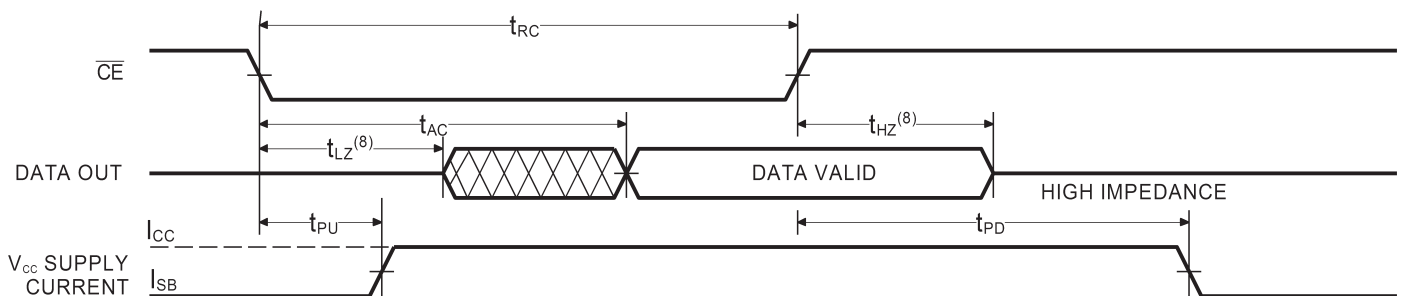
Sym	Parameter	Temperature Range	-10	-12	-15	-20	-25	-35	Unit
I <sub>CC</sub>	Dynamic Operating Current*	Commercial	180	170	160	155	150	140	mA
		Industrial	N/A	180	170	160	155	150	mA
		Military	N/A	N/A	170	160	155	150	mA

\* V<sub>CC</sub> = 5.5V. Tested with outputs open. f = Max. Switching inputs are 0V and 3V.  $\overline{CE} = V_{IL}, \overline{OE} = V_{IH}$ .

### AC ELECTRICAL CHARACTERISTICS—READ CYCLE

(V<sub>CC</sub> = 5V ± 10%, All Temperature Ranges)<sup>(2)</sup>

Sym	Parameter	-10		-12		-15		-20		-25		-35		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>RC</sub>	Read Cycle Time	10		12		15		20		25		35		ns
t <sub>AA</sub>	Address Access Time		10		12		15		20		25		35	ns
t <sub>AC</sub>	Chip Enable Access Time		10		12		15		20		25		35	ns
t <sub>OH</sub>	Output Hold from Address Change	2		2		2		2		2		2		ns
t <sub>LZ</sub>	Chip Enable to Output in Low Z	2		2		2		2		3		3		ns
t <sub>HZ</sub>	Chip Disable to Output in High Z		5		6		7		8		10		15	ns
t <sub>OE</sub>	Output Enable Low to Data Valid		6		8		10		10		15		20	ns
t <sub>OLZ</sub>	Output Enable Low to Low Z	0		0		0		0		0		0		ns
t <sub>OHZ</sub>	Output Enable High to High Z		6		7		8		9		12		15	ns
t <sub>PU</sub>	Chip Enable to Power Up Time	0		0		0		0		0		0		ns
t <sub>PD</sub>	Chip Disable to Power Down		10		12		15		20		20		25	ns

**TIMING WAVEFORM OF READ CYCLE NO. 1 ( $\overline{OE}$  CONTROLLED)<sup>(5)</sup>****TIMING WAVEFORM OF READ CYCLE NO. 2 (ADDRESS CONTROLLED)<sup>(5,6)</sup>****TIMING WAVEFORM OF READ CYCLE NO. 3 ( $\overline{CE}$  CONTROLLED)****Notes:**

- Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to MAXIMUM rating conditions for extended periods may affect reliability.
- Extended temperature operation guaranteed with 400 linear feet per minute of air flow.
- Transient inputs with  $V_L$  and  $I_L$  not more negative than  $-3.0V$  and  $-100mA$ , respectively, are permissible for pulse widths up to 20ns.
- This parameter is sampled and not 100% tested.
- $\overline{WE}$  is HIGH for READ cycle.
- $\overline{CE}$  is LOW and  $\overline{OE}$  is LOW for READ cycle.
- ADDRESS must be valid prior to, or coincident with  $\overline{CE}$  transition LOW.
- Transition is measured  $\pm 200$  mV from steady state voltage prior to change, with loading as specified in Figure 1. This parameter is sampled and not 100% tested.
- Read Cycle Time is measured from the last valid address to the first transitioning address.

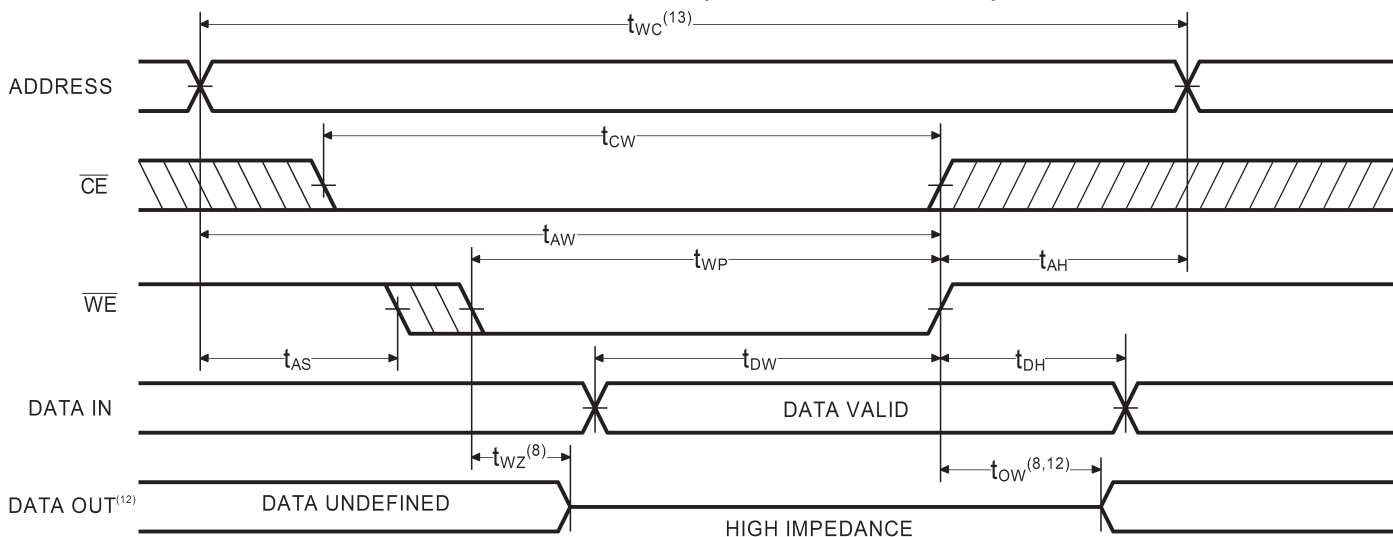


## AC CHARACTERISTICS—WRITE CYCLE

( $V_{CC} = 5V \pm 10\%$ , All Temperature Ranges)<sup>(2)</sup>

Sym	Parameter	-10		-12		-15		-20		-25		-35		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{WC}$	Write Cycle Time	10		12		15		20		25		35		ns
$t_{CW}$	Chip Enable Time to End of Write	8		10		12		15		18		25		ns
$t_{AW}$	Address Valid to End of Write	8		10		12		15		18		25		ns
$t_{AS}$	Address Setup Time	0		0		0		0		0		0		ns
$t_{WP}$	Write Pulse Width	8		10		12		15		18		20		ns
$t_{AH}$	Address Hold Time	0		0		0		0		0		0		ns
$t_{DW}$	Data Valid to End of Write	7		8		10		12		15		20		ns
$t_{DH}$	Data Hold Time	0		0		0		0		0		0		ns
$t_{WZ}$	Write Enable to Output in High Z		6		7		8		10		15		15	ns
$t_{OW}$	Output Active from End of Write	0		0		0		0		0		0		ns

### TIMING WAVEFORM OF WRITE CYCLE NO. 1 ( $\overline{WE}$ CONTROLLED)<sup>(10,11)</sup>



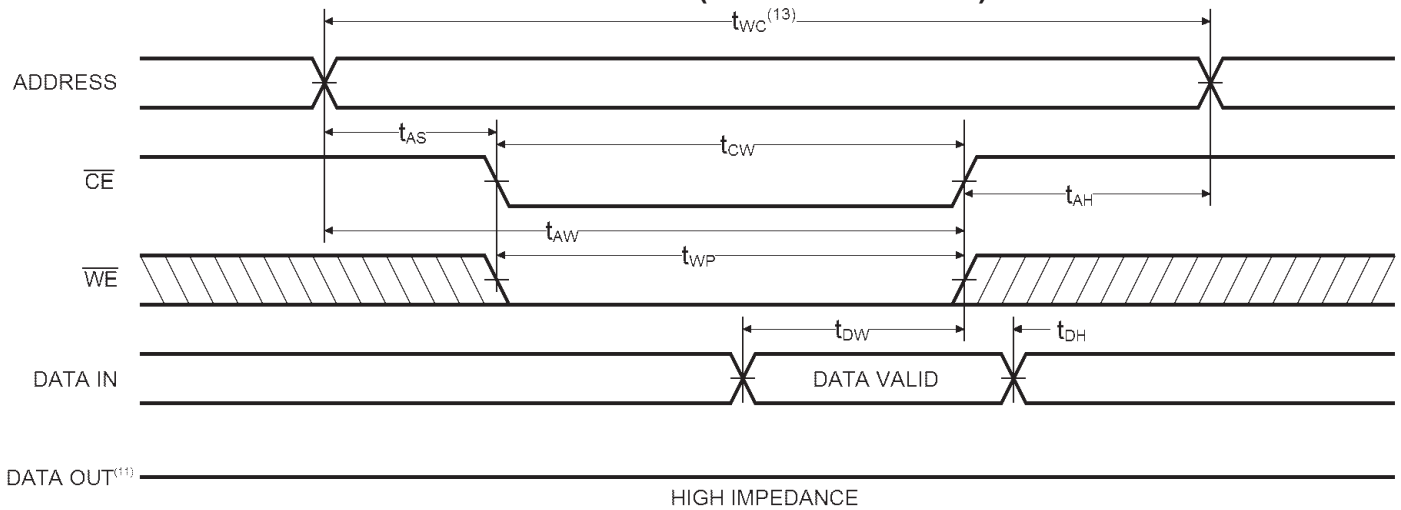
#### Notes:

10.  $\overline{CE}$  and  $\overline{WE}$  must be LOW for WRITE cycle.
11.  $\overline{OE}$  is LOW for this WRITE cycle to show  $t_{WZ}$  and  $t_{OW}$ .
12. If  $\overline{CE}$  goes HIGH simultaneously with  $\overline{WE}$  HIGH, the output remains in a high impedance state.

13. Write Cycle Time is measured from the last valid address to the first transitioning address.



### TIMING WAVEFORM OF WRITE CYCLE NO. 2 ( $\overline{CE}$ CONTROLLED)<sup>(10)</sup>



### AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise and Fall Times	3ns
Input Timing Reference Level	1.5V
Output Timing Reference Level	1.5V
Output Load	See Figures 1 and 2

### TRUTH TABLE

Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	I/O	Power
Standby	H	X	X	High Z	Standby
D <sub>OUT</sub> Disabled	L	H	H	High Z	Active
Read	L	L	H	D <sub>OUT</sub>	Active
Write	L	X	L	High Z	Active

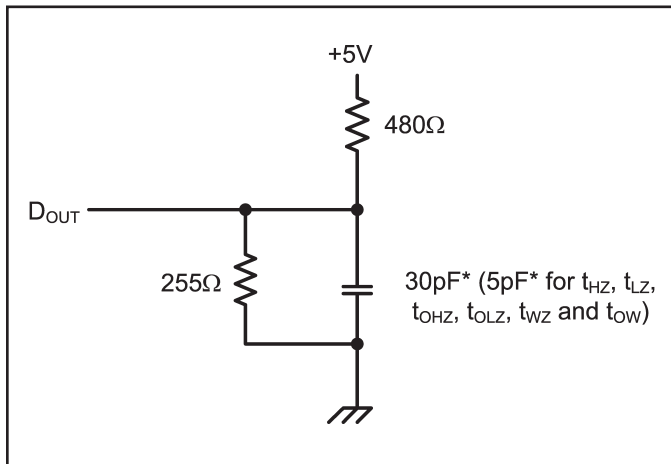


Figure 1. Output Load

\* including scope and test fixture.

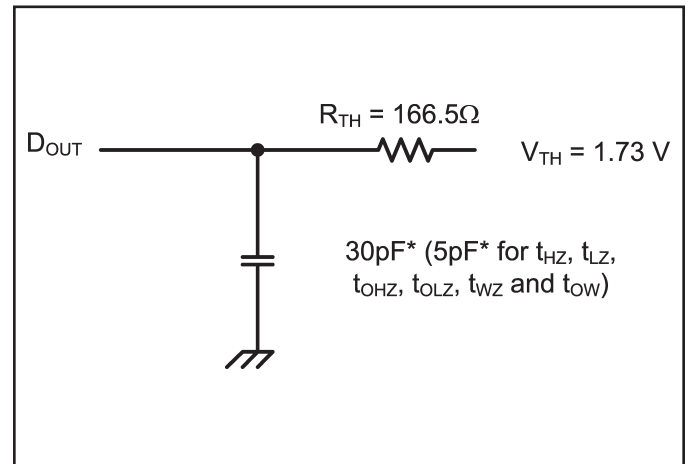


Figure 2. Thevenin Equivalent

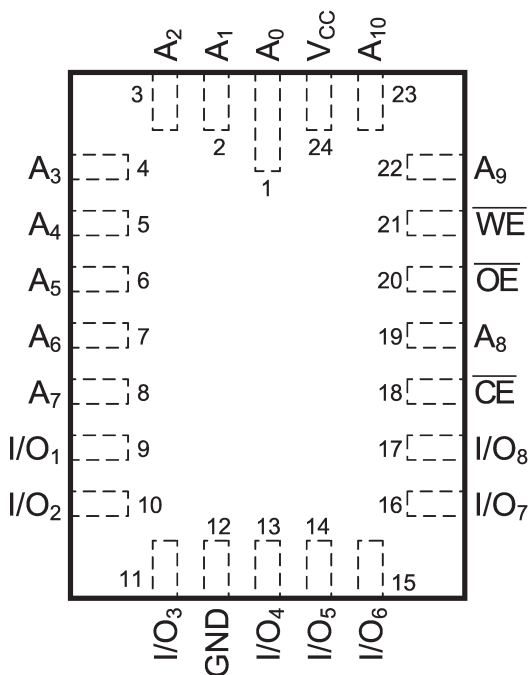
**Note:**

Because of the ultra-high speed of the P4C116/L, care must be taken when testing this device; an inadequate setup can cause a normal functioning part to be rejected as faulty. Long high-inductance leads that cause supply bounce must be avoided by bringing the V<sub>CC</sub> and ground planes directly up to the contactor fingers. A 0.01 μF high frequency capacitor

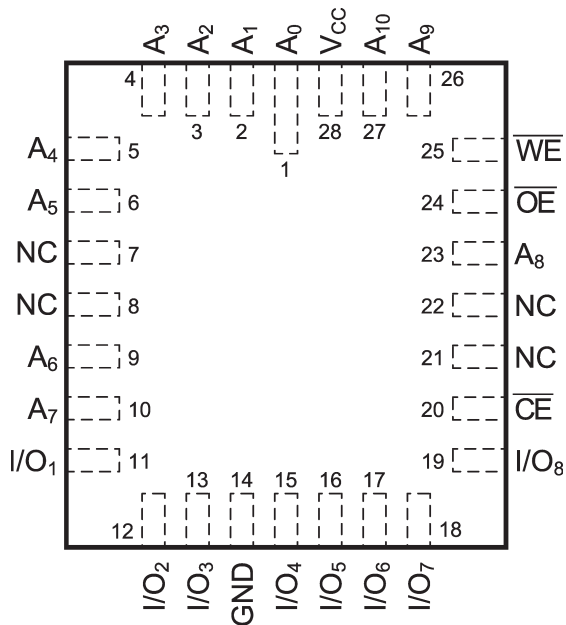
is also required between V<sub>CC</sub> and ground. To avoid signal reflections, proper termination must be used; for example, a 50Ω test environment should be terminated into a 50Ω load with 1.73V (Thevenin Voltage) at the comparator input, and a 116Ω resistor must be used in series with D<sub>OUT</sub> to match 166Ω (Thevenin Resistance).



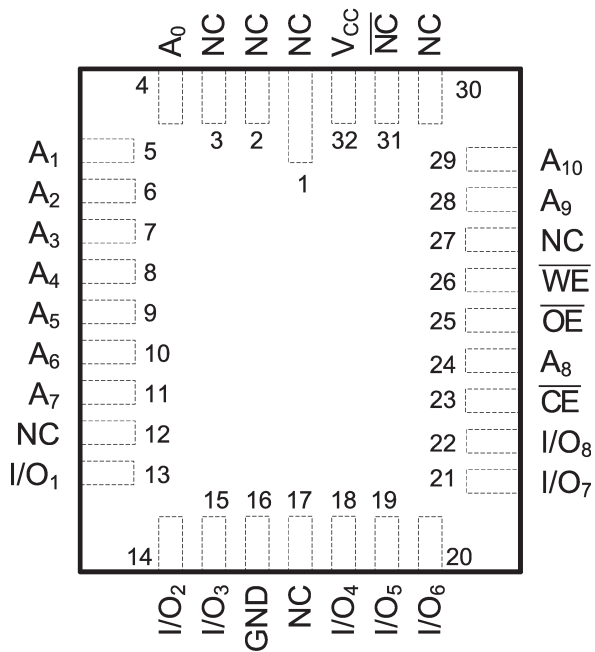
# LCC PIN CONFIGURATIONS



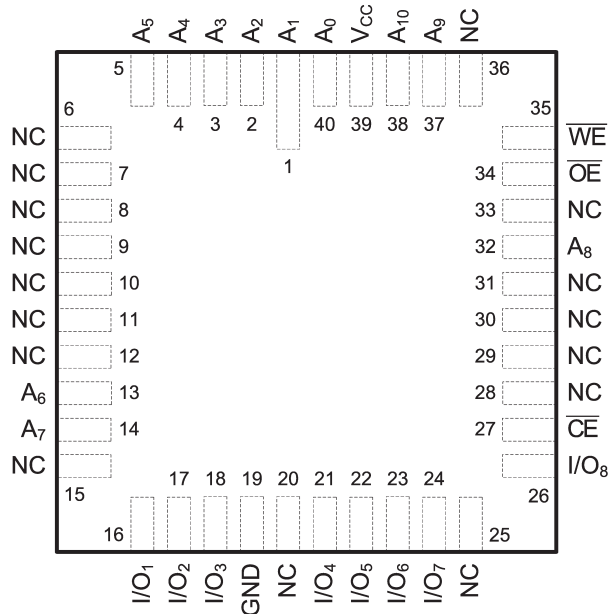
24-Pin LCC (L8)



28-Pin LCC (L5-1)



32-Pin LCC (L6)



40-Pin LCC (L10)



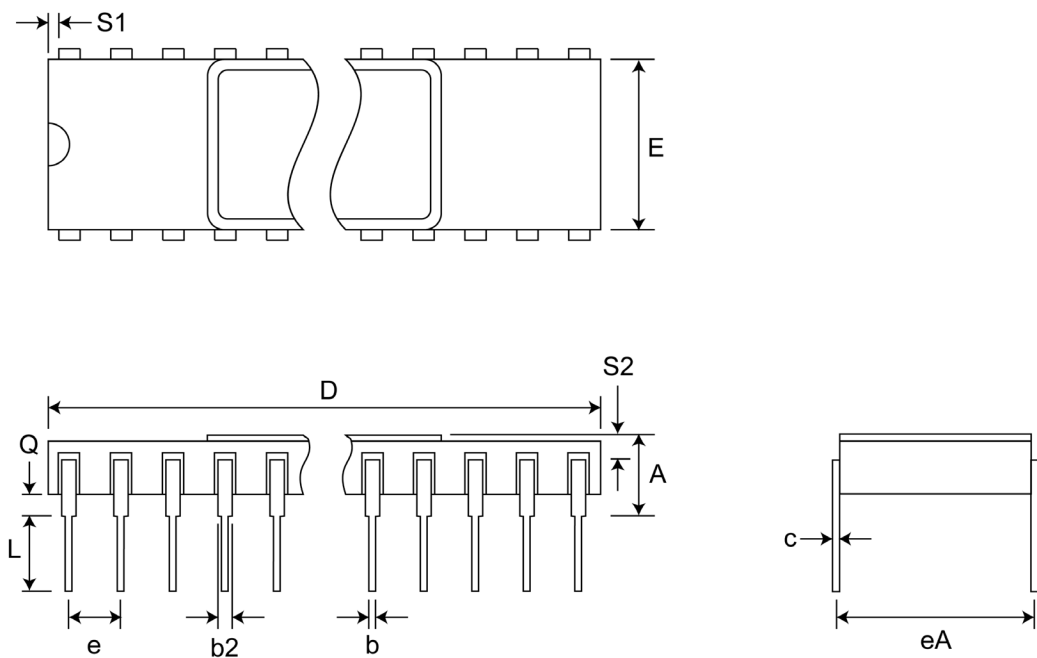
### ORDERING INFORMATION

P4C116	L	xx	x	x	
Device Type	Low Power	Speed	Package	Processing	
				C	0°C to +70°C
				I	-40°C to +85°C
				M	-55°C to +125°C
				MB	Mil Temp with MIL-STD-883 Class B Compliance
				C	Ceramic Side Brazed DIP, 300 mil
				CW	Ceramic Side Brazed DIP, 600 mil
				D	Ceramic CERDIP, 300 mil
				FS	Solder Seal Flat Pack
				J	Plastic SOJ, 300 mil
				L	24-Pin Rectangular LCC (300 x 400 mil)
				L28	28-Pin Square LCC (450 x 450 mil)
				L32	32-Pin Rectangular LCC (450 x 550 mil)
				L40	40-Pin Square LCC (480 x 480 mil)
				P	Plastic DIP, 300 mil
				S	Plastic SOIC, 300 mil
					10, 12, 15, 20, 25, 35
					Low Power Designation (L=Low Power; Blank=None)
					2K x 8 SRAM



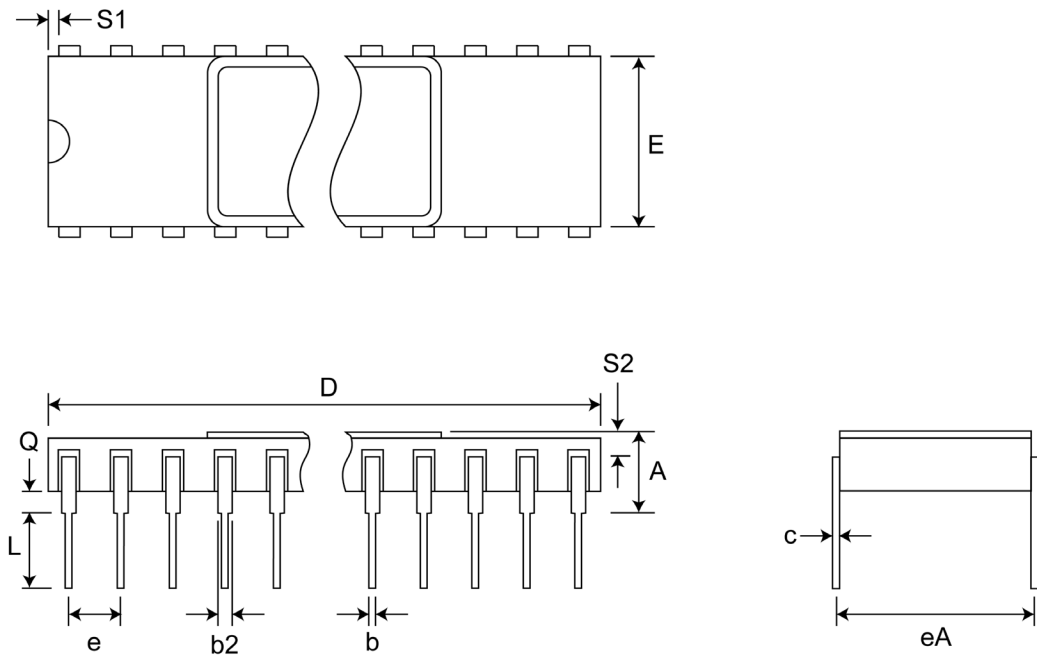
Pkg #	<b>C4</b>	
# Pins	24 (300 mil)	
Symbol	Min	Max
A	-	0.200
b	0.014	0.026
b2	0.045	0.065
C	0.008	0.018
D	-	1.280
E	0.220	0.310
eA	0.300 BSC	
e	0.100 BSC	
L	0.125	0.200
Q	0.015	0.060
S1	0.005	-
S2	0.005	-

**SIDEBRAZED DUAL IN-LINE PACKAGE**



Pkg #	<b>C12</b>	
# Pins	24 (600 mil)	
Symbol	Min	Max
A	-	0.232
b	0.014	0.026
b2	0.045	0.065
C	0.008	0.018
D	-	1.290
E	0.500	0.610
eA	0.600 BSC	
e	0.100 BSC	
L	0.125	0.200
Q	0.015	0.060
S1	0.005	-
S2	0.005	-

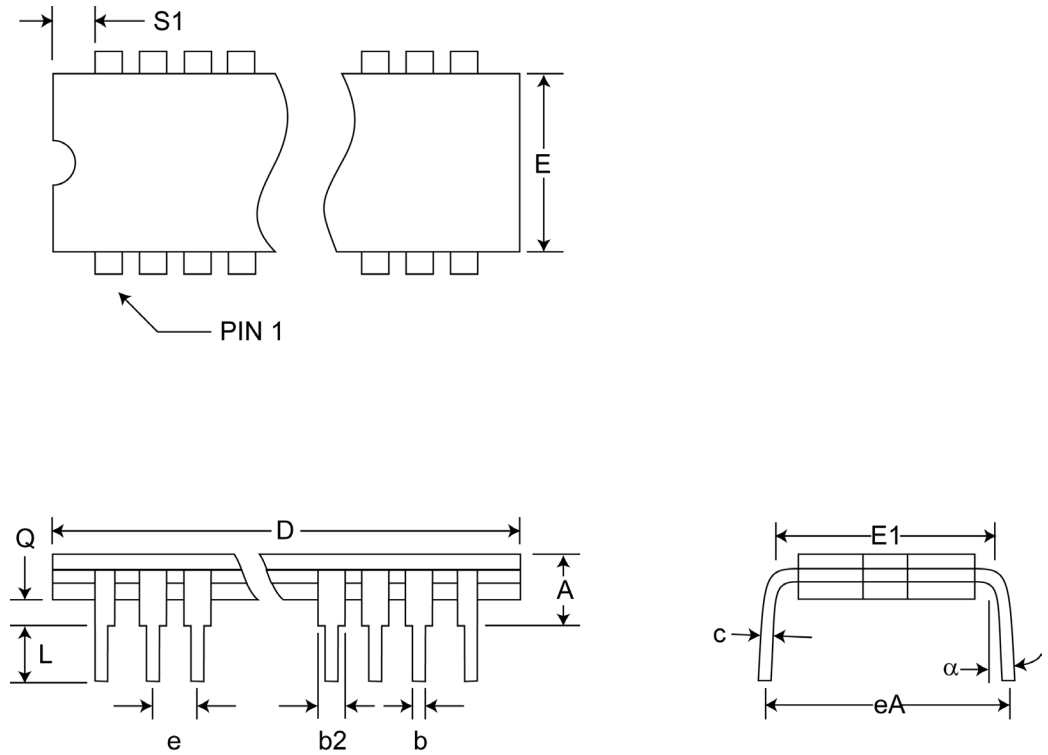
**SIDEBRAZED DUAL IN-LINE PACKAGE**





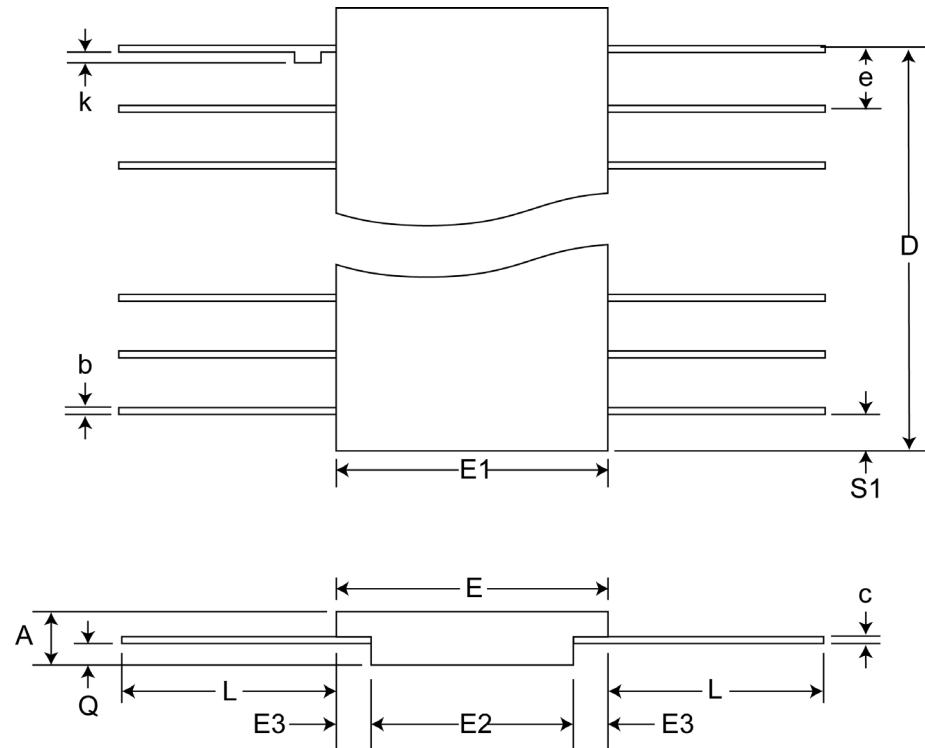
Pkg #	D4	
# Pins	24 (300 mil)	
Symbol	Min	Max
A	-	0.200
b	0.014	0.026
b2	0.045	0.065
C	0.008	0.018
D	-	1.280
E	0.220	0.310
eA	0.300 BSC	
e	0.100 BSC	
L	0.125	0.200
Q	0.015	0.060
S1	0.005	-
S2	0°	15°

**CERDIP DUAL INLINE PACKAGE**



Pkg #	FS-1	
# Pins	24	
Symbol	Min	Max
A	0.045	0.115
b	0.015	0.022
b1	0.015	0.019
c	0.004	0.009
c1	0.004	0.006
D	-	0.640
E	0.350	0.420
E1	-	0.450
E2	0.180	-
E3	0.030	-
e	0.050 BSC	
k	0.008	0.015
L	0.250	0.370
Q	0.026	0.045
S1	0.000	-
M	-	0.002
N	24	

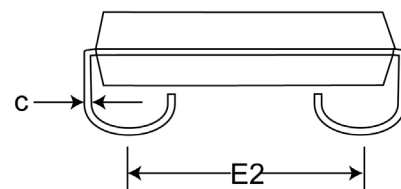
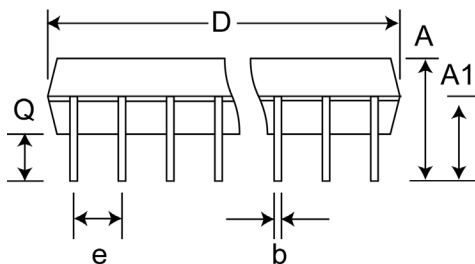
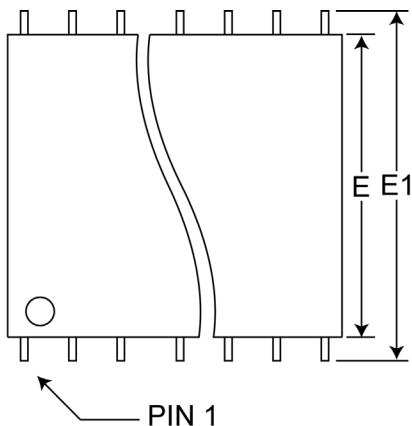
**SOLDER SEAL FLATPACK**





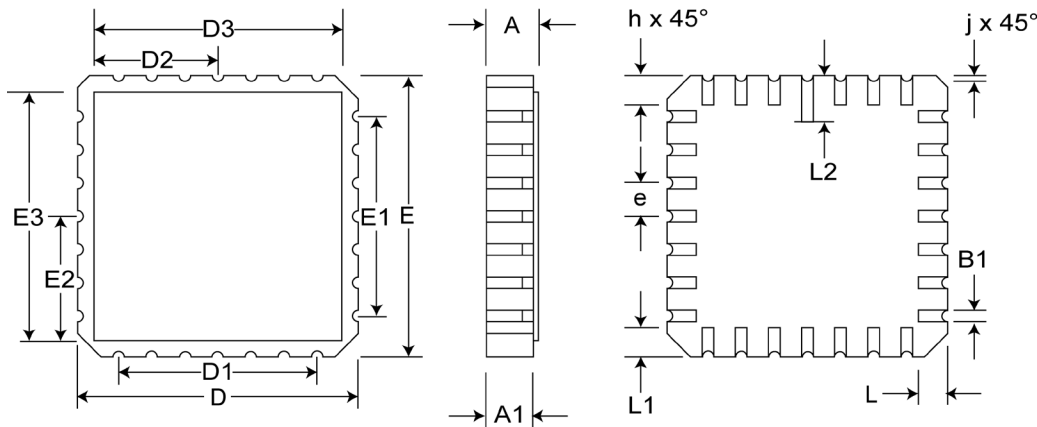
**SOJ SMALL OUTLINE IC PACKAGE**

Pkg #	<b>J4</b>	
# Pins	24 (300 mil)	
Symbol	<b>Min</b>	<b>Max</b>
A	0.128	0.148
A1	0.082	-
b	0.016	0.020
C	0.007	0.010
D	0.620	0.630
e	0.050 BSC	
E	0.335 BSC	
E1	0.292	0.300
E2	0.267 BSC	
Q	0.025	-



Pkg #	<b>L5-1</b>	
# Pins	28	
Symbol	<b>Min</b>	<b>Max</b>
A	0.060	0.075
A1	0.050	0.065
B1	0.022	0.028
D/E	0.442	0.460
D1/E1	0.300 BSC	
D2/E2	0.150 BSC	
D3/E3	-	0.460
e	0.050 BSC	
h	0.040 REF	
j	0.020 REF	
L	0.045	0.055
L1	0.045	0.055
L2	0.075	0.095
ND	7	
NE	7	

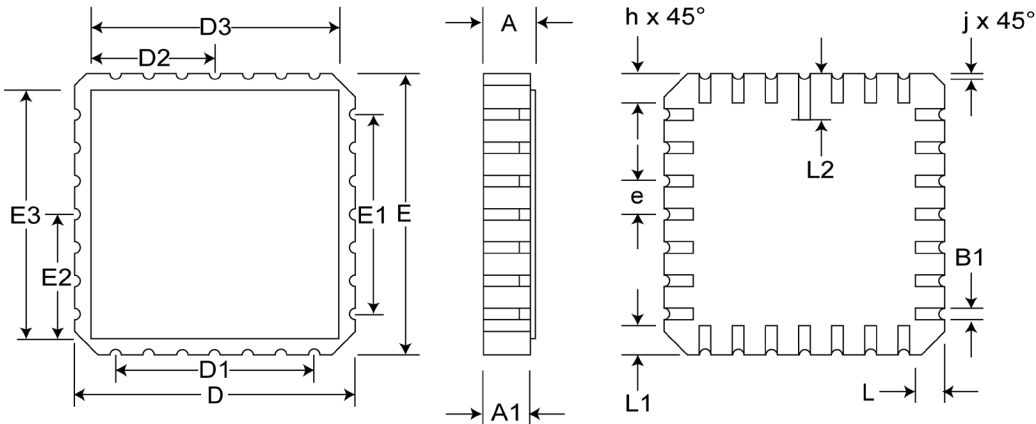
**SQUARE LEADLESS CHIP CARRIER**





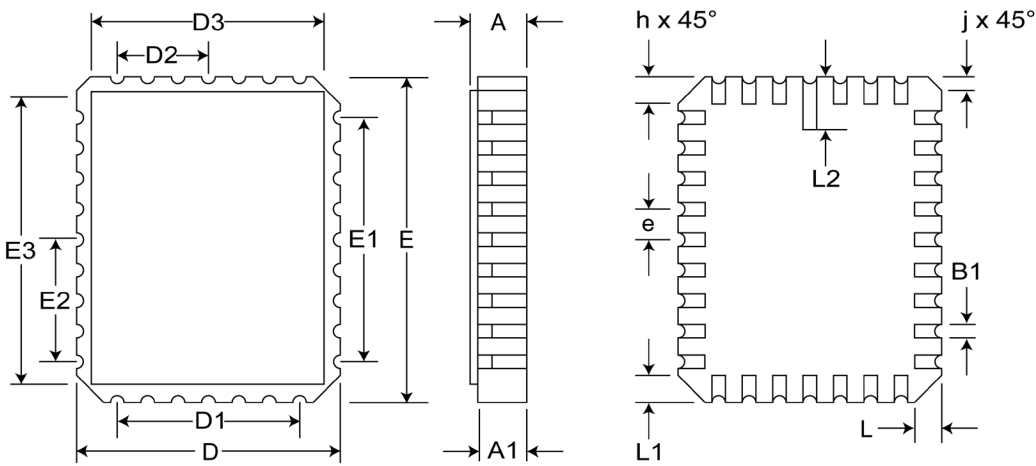
**SQUARE LEADLESS CHIP CARRIER**

Pkg #	<b>L10</b>	
# Pins	40	
Symbol	<b>Min</b>	<b>Max</b>
A	0.060	0.080
A1	0.050	0.075
B1	0.015	0.025
D/E	0.475	0.492
D1/E1	0.360 BSC	
D2/E2	0.180 BSC	
D3/E3	-	0.492
e	0.040 BSC	
h	R = .0075	
j	0.026 REF	
L	0.030	0.050
L1	0.030	0.050
L2	0.080	0.090
ND	10	
NE	10	



**RECTANGULAR LEADLESS CHIP CARRIER**

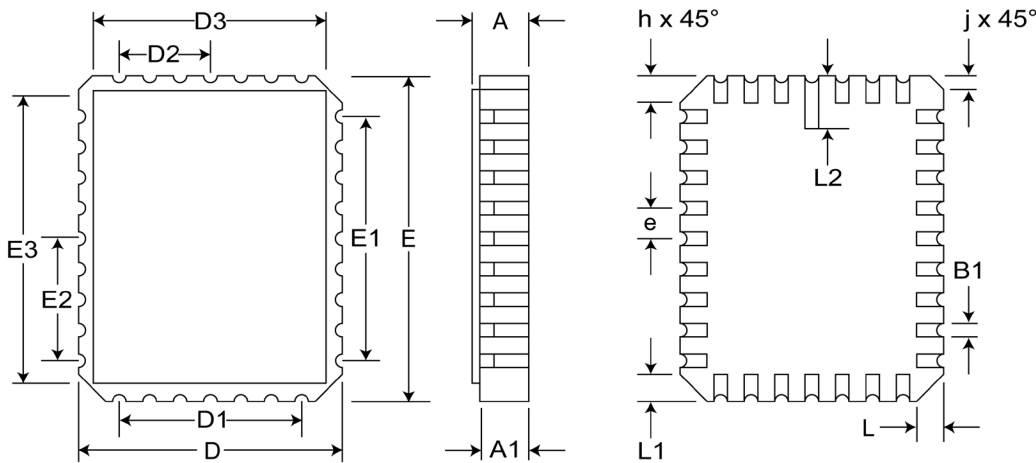
Pkg #	<b>L6</b>	
# Pins	32	
Symbol	<b>Min</b>	<b>Max</b>
A	0.060	0.075
A1	0.050	0.065
B1	0.022	0.028
D	0.442	0.458
D1	0.300 BSC	
D2	0.150 BSC	
D3	-	0.458
E	0.540	0.560
E1	0.400 BSC	
E2	0.200 BSC	
E3	-	0.558
e	0.050 BSC	
h	0.040 REF	
j	0.020 REF	
L	0.045	0.055
L1	0.045	0.055
L2	0.075	0.095
ND	7	
NE	9	





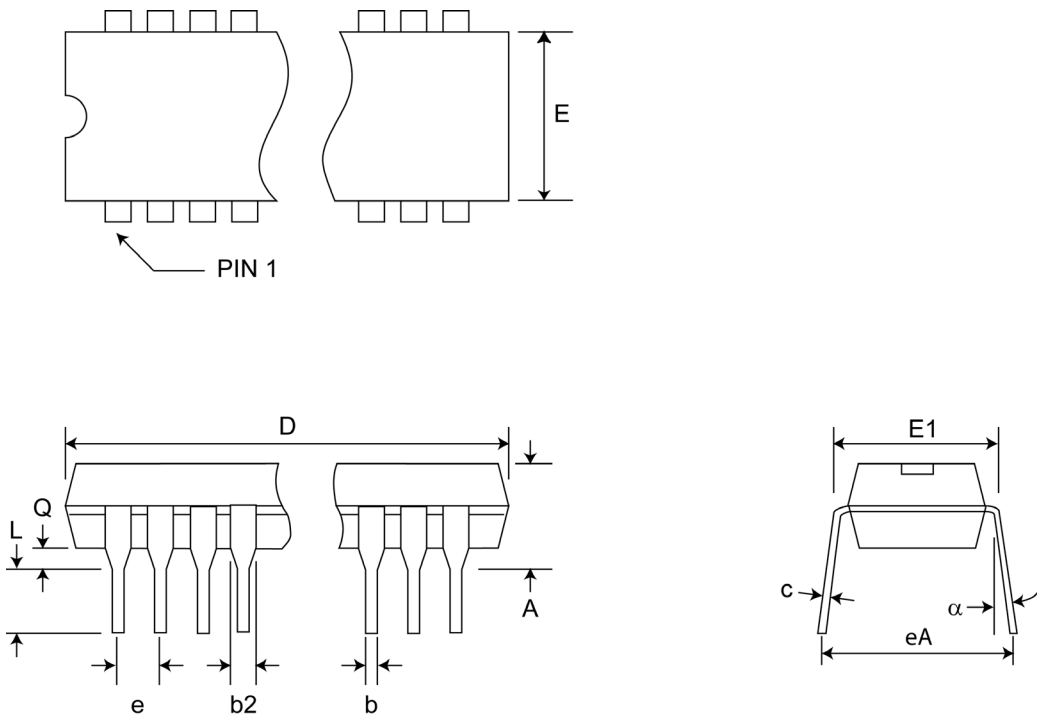
Pkg #	<b>L8</b>	
# Pins	24	
Symbol	<b>Min</b>	<b>Max</b>
A	0.064	0.076
A1	0.054	0.066
B1	0.022	0.028
D	0.292	0.308
D1	0.200 BSC	
D2	0.100 BSC	
D3	-	0.308
E	0.392	0.408
E1	0.300 BSC	
E2	0.150 BSC	
E3	-	0.408
e	0.050 BSC	
h	0.025 REF	
j	0.015 REF	
L	0.040	0.050
L1	0.040	0.050
L2	0.077	0.093
ND	5	
NE	7	

**RECTANGULAR LEADLESS CHIP CARRIER**



Pkg #	<b>P4</b>	
# Pins	24 (300 Mil)	
Symbol	<b>Min</b>	<b>Max</b>
A	-	0.210
A1	0.015	-
b	0.014	0.022
b2	0.045	0.070
C	0.008	0.014
D	1.230	1.280
E1	0.240	0.280
E	0.280	0.325
e	0.100 BSC	
eB	-	0.430
L	0.115	0.160
$\alpha$	0°	15°

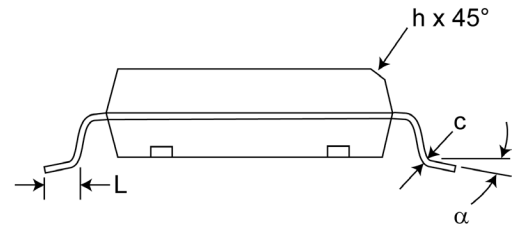
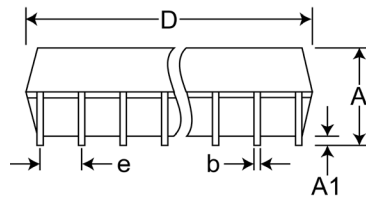
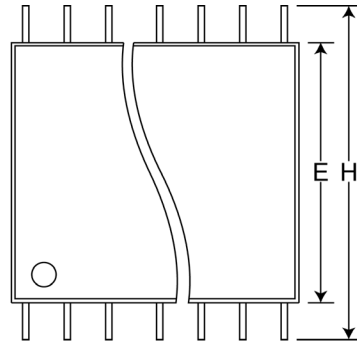
**PLASTIC DUAL IN-LINE PACKAGE**





**SOIC/SOP SMALL OUTLINE IC PACKAGE**

Pkg #	<b>S4</b>	
# Pins	24 (300 Mil)	
Symbol	<b>Min</b>	<b>Max</b>
A	0.093	0.104
A1	0.004	0.012
b2	0.013	0.020
C	0.009	0.012
D	0.598	0.614
e	0.050 BSC	
E	0.291	0.299
H	0.394	0.419
h	0.010	0.029
L	0.016	0.050
$\alpha$	0°	8°



**REVISIONS**

<b>DOCUMENT NUMBER</b>	SRAM 110
<b>DOCUMENT TITLE</b>	P4C116 / P4C116L ULTRA HIGH SPEED 2K X 8 STATIC CMOS RAMS

<b>REV</b>	<b>ISSUE DATE</b>	<b>ORIGINATOR</b>	<b>DESCRIPTION OF CHANGE</b>
OR	1997	DAB	New Data Sheet
A	Oct-2005	JDB	Changed logo to Pyramid
B	Feb-2009	JDB	Added Industrial Temperature Range
C	May-2009	JDB	Added 300 mil CERDIP and 600 mil sidebrazed packages